N-Channel Enhancement Mode MOSFET

BL085N03D

Features

HF

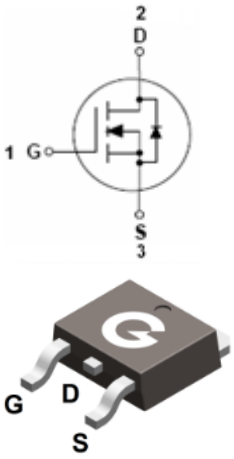
- Advanced trench technology
- Low on-resistance
- Fast switching speed
- RoHS compliant with Halogen-free

Applications

- Synchronous Rectification
- Motor Control
- Portable equipment application

Mechanical Data

- Case: TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



TO-252

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL085N03D	TO-252	80 pcs / Tube & 2500 pcs / Tape & Reel	085N03D

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	30	V
Gate-to-Source Voltage	V_{GSS}	±20	V
Continuous Drain Current (T_C = 25°C)	I_D	65	A
Continuous Drain Current (T_C = 100°C)		41	A
Continuous Drain Current (T_A = 25°C) *1		15	A
Continuous Drain Current (T_A = 100°C) *1		9.5	A
Pulsed Drain Current (t_p = 10μs, T_C = 25°C)	I_{DM}	260	A
Single Pulse Avalanche Energy *3	E_{AS}	57.8	mJ
Power Dissipation (T_C = 25°C)	P_D	57	W
Operating Junction Temperature Range	T_J	-55 ~ +150	°C
Storage Temperature Range	T_{STG}	-55 ~ +150	°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	1.9	2.2	°C/W
Thermal Resistance Junction-to-Air *1	$R_{\theta JA}$	-	30	52	°C/W

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 30V, V_{GS} = 0V	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance *2	V_{GS} = 10V,I_D = 30A	-	6	8.5	mΩ
		V_{GS} = 4.5V,I_D = 15A	-	11	14	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.7	2.5	V
R_G	Gate Resistance	V_{GS} = 0V, f = 1MHz	-	3.5	-	Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	V_{GS} = 0V V_{DS} = 15V f = 1.0MHz	-	1080	-	pF
C_{OSS}	Output Capacitance		-	156	-	
C_{RSS}	Reverse Transfer Capacitance		-	128	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	V_{DD} = 30V V_{GS} = 15V I_D = 15A R_G = 3.3Ω	-	7	-	ns
t_r	Turn-on Rise Time		-	17	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	40	-	
t_f	Turn-Off Fall Time		-	12	-	
Q_G	Total Gate-Charge(V_{GS} = 4.5V)	V_{DD} = 15V V_{GS} = 10V I_D = 15A	-	10.3	-	nC
	Total Gate-Charge(V_{GS} = 10V)			20.8		
Q_{GS}	Gate to Source Charge		-	3.5	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	4.8	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *2	I_{SD} = 5A, V_{GS} = 0V	-	0.8	1.2	V
trr	Reverse Recovery Time	I_S = 15A, V_{GS} = 0V di/dt = 100A/μs	-	97	-	ns
Qrr	Reverse Recovery Charge		-	57	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E_{AS} data shows Max. rating. The test condition is V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH

Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

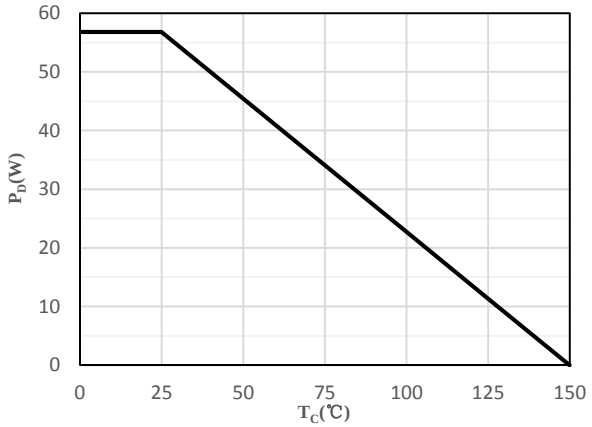


Fig 1 Power Dissipation

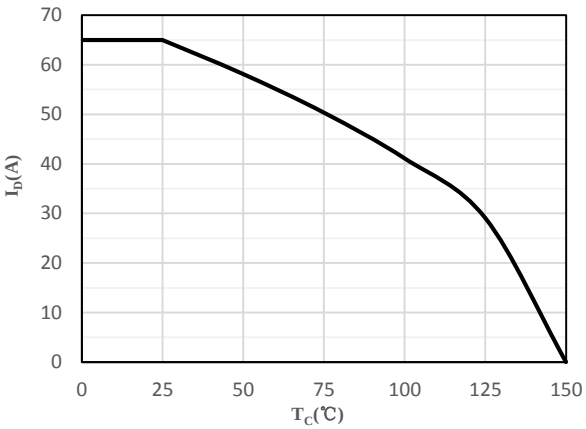


Fig 2 Drain Current

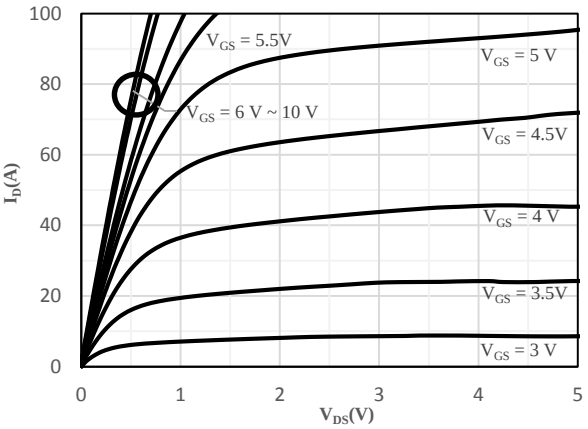


Fig 3 Typical Output Characteristics

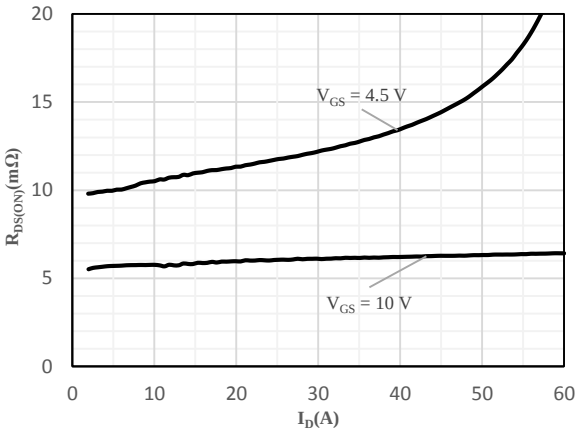


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

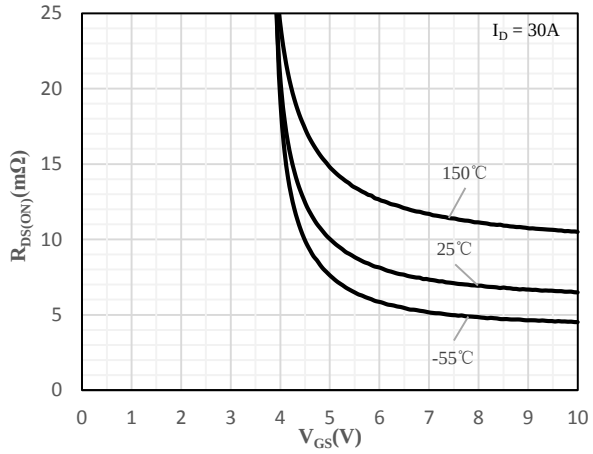


Fig 5 On-Resistance vs. Gate-Source Voltage

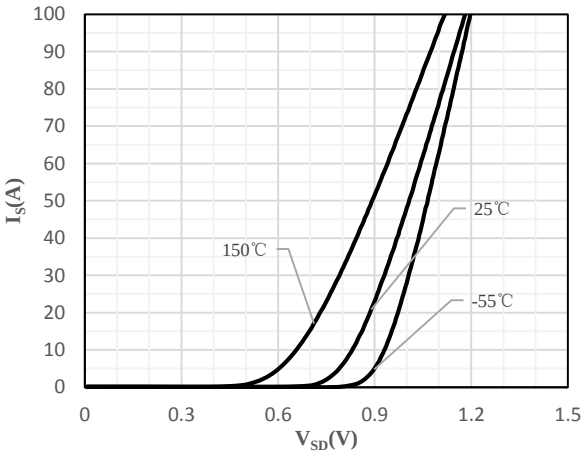


Fig 6 Body-Diode Characteristics

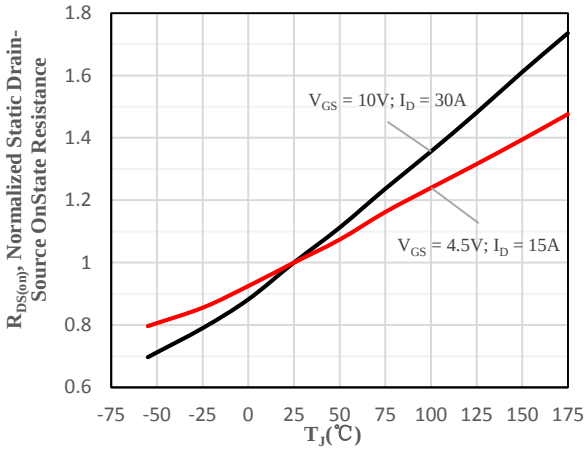


Fig 7 Normalized On-Resistance vs. Junction Temperature

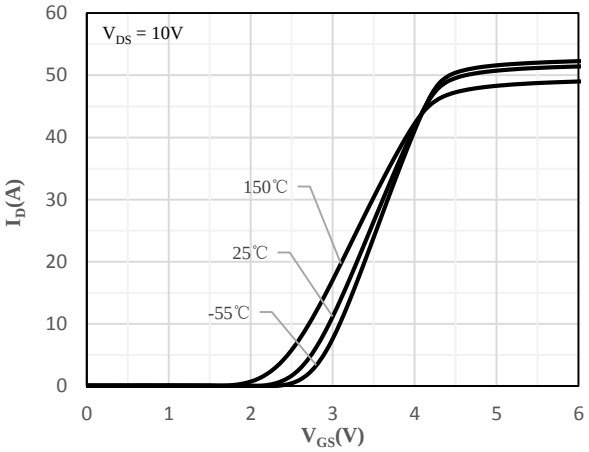


Fig 8 Transfer Characteristics

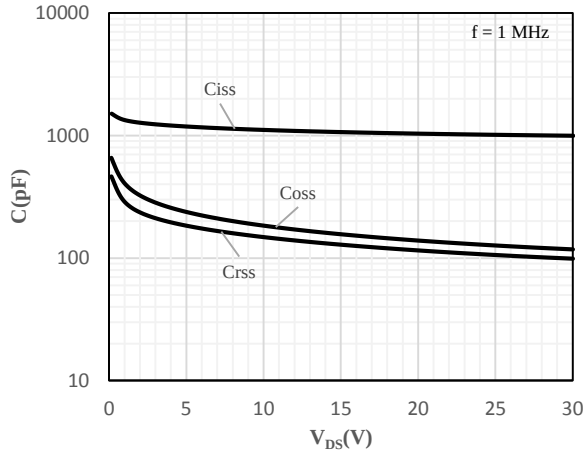


Fig 9 Capacitance Characteristics

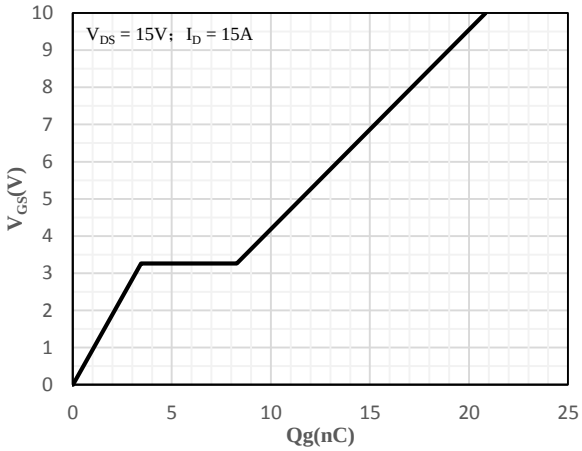


Fig 10 Gate-Charge Characteristics

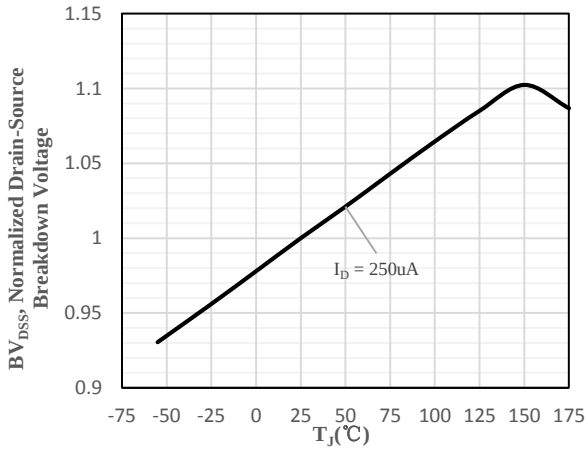


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

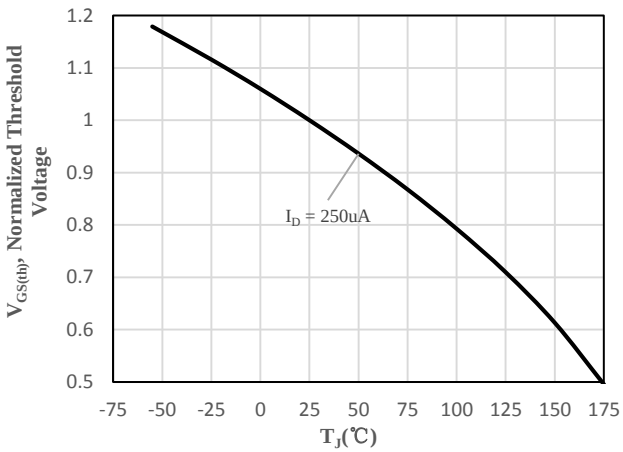


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

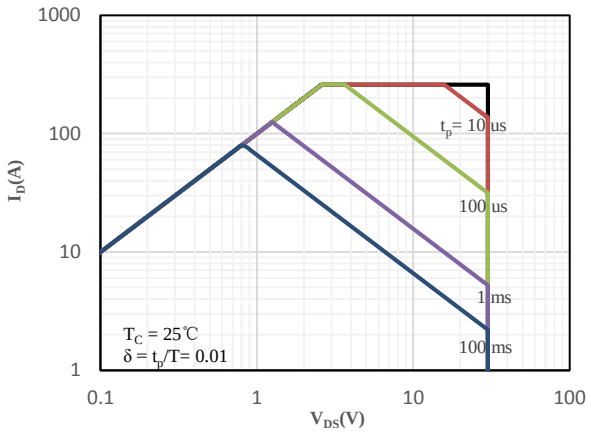


Fig 13 Safe Operating Area

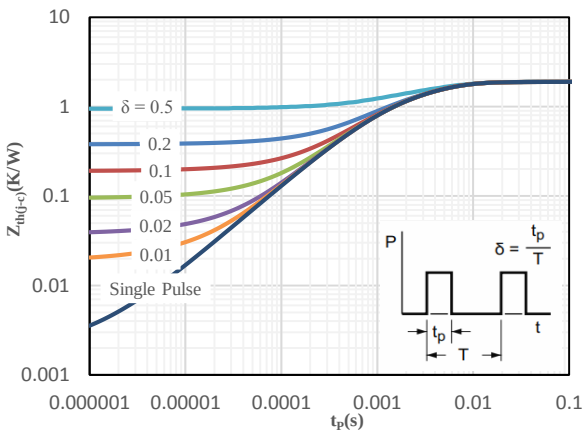
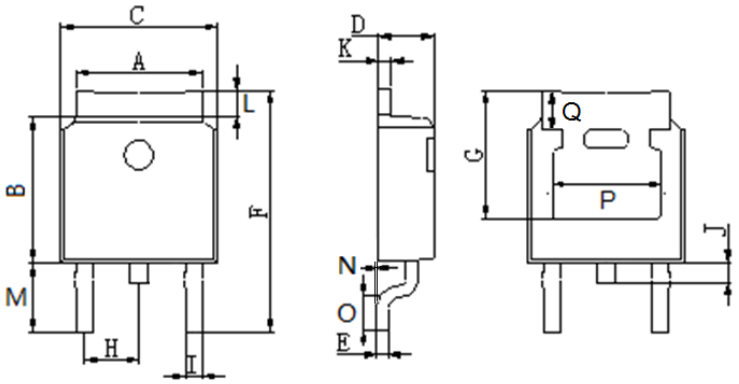


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



TO-252		
Dimension	**Min.**	**Max.**
A	5.05	5.65
B	5.80	6.40
C	6.25	6.85
D	2.20	2.40
E	0.40	0.60
F	9.71	10.31
G	5.05	5.65
H	2.10	2.50
I	0.70	0.90
J	0.50	0.7
K	0.40	0.60
L	0.80	1.20
M	2.70	3.10
N	0.00	0.12
O	1.10	1.50
P	4.70	4.90
Q	1.25	1.45

Mounting Pad Layout (Unit: mm)

TO-252